Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f675-e-sn

2.2.2.6 PCON Register

The Power Control (PCON) register contains flag bits to differentiate between a:

- Power-on Reset (POR)
- Brown-out Detect (BOD)
- Watchdog Timer Reset (WDT)
- External $\overline{MCLR}$ Reset

The PCON Register bits are shown in Register 2-6.

REGISTER 2-6: PCON: POWER CONTROL REGISTER (ADDRESS: 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-x
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOD}$
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **$\overline{POR}$:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOD}$:** Brown-out Detect Status bit
1 = No Brown-out Detect occurred
0 = A Brown-out Detect occurred (must be set in software after a Brown-out Detect occurs)

2.2.2.7 OSCCAL Register

The Oscillator Calibration register (OSCCAL) is used to calibrate the internal 4 MHz oscillator. It contains 6 bits to adjust the frequency up or down to achieve 4 MHz.

The OSCCAL register bits are shown in Register 2-7.

REGISTER 2-7: OSCCAL: OSCILLATOR CALIBRATION REGISTER (ADDRESS: 90h)

R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2 **CAL5:CAL0:** 6-bit Signed Oscillator Calibration bits
111111 = Maximum frequency
100000 = Center frequency
000000 = Minimum frequency

bit 1-0 **Unimplemented:** Read as '0'

3.2.2 INTERRUPT-ON-CHANGE

Each of the GPIO pins is individually configurable as an interrupt-on-change pin. Control bits IOC enable or disable the interrupt function for each pin. Refer to Register 3-4. The interrupt-on-change is disabled on a Power-on Reset.

For enabled interrupt-on-change pins, the values are compared with the old value latched on the last read of GPIO. The 'mismatch' outputs of the last read are OR'd together to set, the GP Port Change Interrupt flag bit (GPIF) in the INTCON register.

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of GPIO. This will end the mismatch condition.

b) Clear the flag bit GPIF.

A mismatch condition will continue to set flag bit GPIF. Reading GPIO will end the mismatch condition and allow flag bit GPIF to be cleared.

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the GPIF interrupt flag may not get set.

REGISTER 3-4: IOC: INTERRUPT-ON-CHANGE GPIO REGISTER (ADDRESS: 96h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	IOC5	IOC4	IOC3	IOC2	IOC1	IOC0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented**: Read as '0'

bit 5-0 **IOC<5:0>:** Interrupt-on-Change GPIO Control bits

1 = Interrupt-on-change enabled
0 = Interrupt-on-change disabled

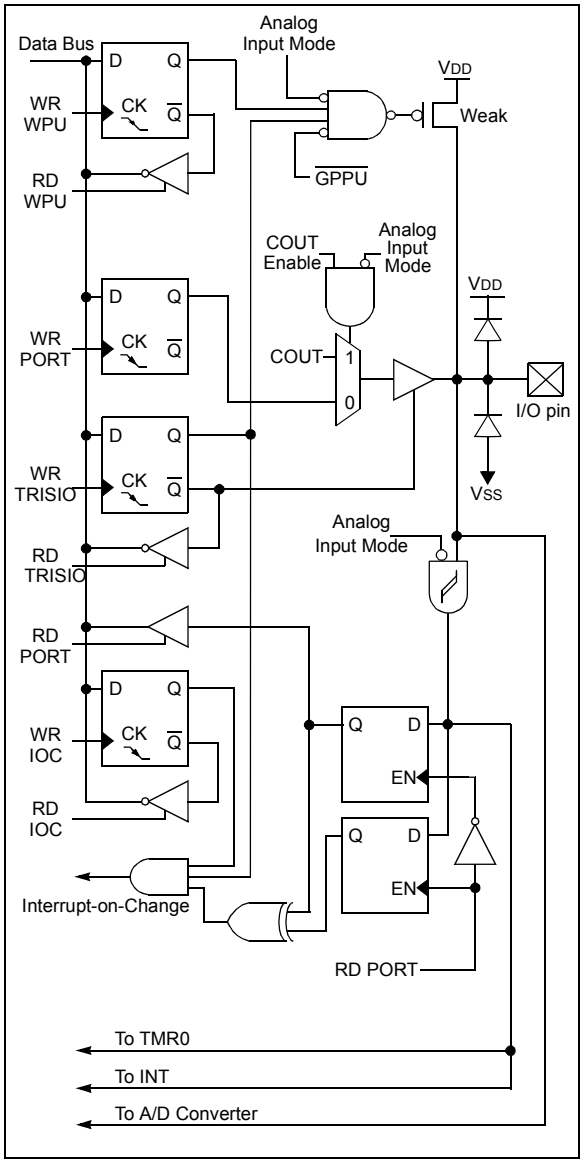
Note 1: Global Interrupt Enable (GIE) must be enabled for individual interrupts to be recognized.

3.3.3 GP2/AN2/T0CKI/INT/COUT

Figure 3-2 shows the diagram for this pin. The GP2 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D (PIC12F675 only)
- the clock input for TMR0
- an external edge triggered interrupt
- a digital output from the comparator

FIGURE 3-2: BLOCK DIAGRAM OF GP2

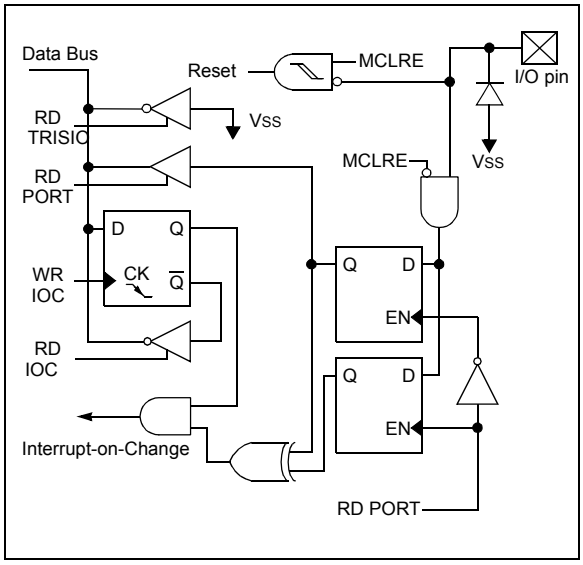


3.3.4 GP3/$\overline{MCLR}$/VPP

Figure 3-3 shows the diagram for this pin. The GP3 pin is configurable to function as one of the following:

- a general purpose input
- as Master Clear Reset

FIGURE 3-3: BLOCK DIAGRAM OF GP3



5.4 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (**Section 5.4.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	The ANSEL (9Fh) and CMCON (19h) registers must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'. The ANSEL register is defined for the PIC12F675.

5.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L, while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Examples 12-2 and 12-3 in the PIC® Mid-Range MCU Family Reference Manual (DS33023) show how to read and write Timer1 when it is running in Asynchronous mode.

5.5 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins OSC1 (input) and OSC2 (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator rated up to 37 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. Table 9-2 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is shared with the system LP oscillator. Thus, Timer1 can use this mode only when the system clock is derived from the internal oscillator. As with the system LP oscillator, the user must provide a software time delay to ensure proper oscillator start-up.

While enabled, TRISIO4 and TRISIO5 are set. GP4 and GP5 read '0' and TRISIO4 and TRISIO5 are read '1'.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to enabling Timer1.

5.6 Timer1 Operation During Sleep

Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To setup the timer to wake the device:

- Timer1 must be on (T1CON<0>)
- TMR1IE bit (PIE1<0>) must be set
- PEIE bit (INTCON<6>) must be set

The device will wake-up on an overflow. If the GIE bit (INTCON<7>) is set, the device will wake-up and jump to the Interrupt Service Routine on an overflow.

TABLE 5-1: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00-- 0--0	00-- 0--0
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	-000 0000	-uuu uuuu
8Ch	PIE1	EEIE	ADIE	—	—	CMIE	—	—	TMR1IE	00-- 0--0	00-- 0--0

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

6.1 Comparator Operation

A single comparator is shown in Figure 6-1, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 6-1 represent the uncertainty due to input offsets and response time.

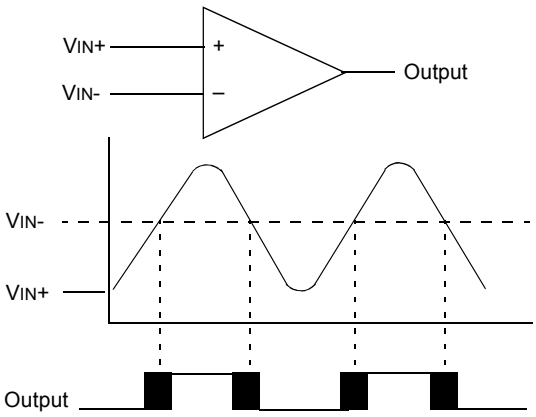
Note:	To use CIN+ and CIN- pins as analog inputs, the appropriate bits must be programmed in the CMCON (19h) register.

The polarity of the comparator output can be inverted by setting the CINV bit (CMCON<4>). Clearing CINV results in a non-inverted output. A complete table showing the output state versus input conditions and the polarity bit is shown in Table 6-1.

TABLE 6-1: OUTPUT STATE VS. INPUT CONDITIONS

Input Conditions	CINV	COUT
VIN- > VIN+	0	0
VIN- < VIN+	0	1
VIN- > VIN+	1	1
VIN- < VIN+	1	0

FIGURE 6-1: SINGLE COMPARATOR

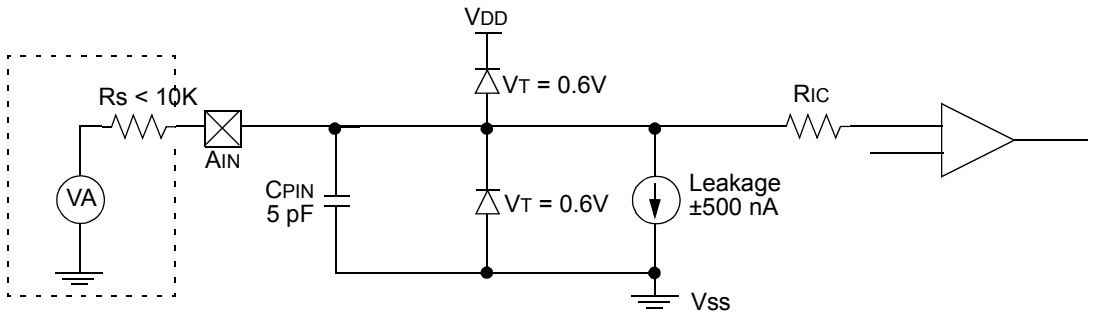


Note: CINV bit (CMCON<4>) is clear.

6.3 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 6-3. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSS. The analog input, therefore, must be between VSS and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 6-3: ANALOG INPUT MODE



Legend:

CPIN	= Input Capacitance
VT	= Threshold Voltage
ILEAKAGE	= Leakage Current at the pin due to Various Junctions
RIC	= Interconnect Resistance
RS	= Source Impedance
VA	= Analog Voltage

6.4 Comparator Output

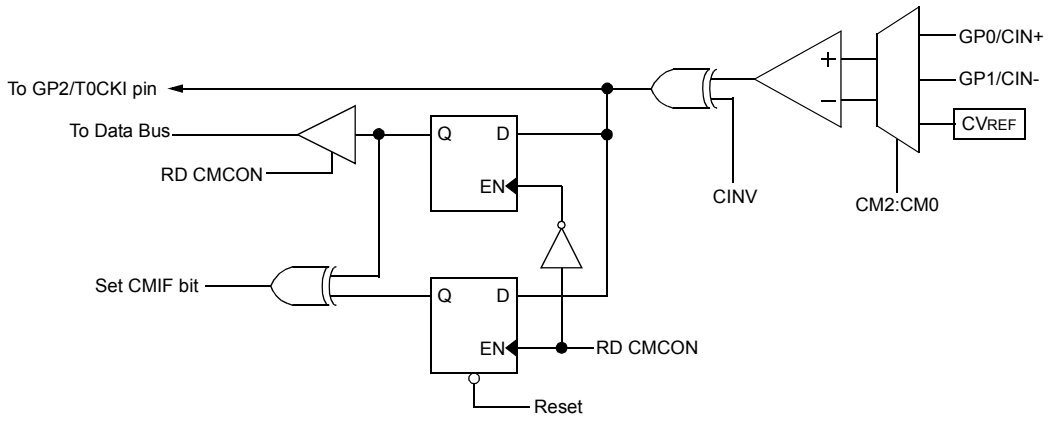
The comparator output, COUT, is read through the CMCON register. This bit is read-only. The comparator output may also be directly output to the GP2 pin in three of the eight possible modes, as shown in Figure 6-2. When in one of these modes, the output on GP2 is asynchronous to the internal clock. Figure 6-4 shows the comparator output block diagram.

The TRISIO<2> bit functions as an output enable/ disable for the GP2 pin while the comparator is in an Output mode.

Note 1: When reading the GPIO register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert an analog input according to the TTL input specification.

2: Analog levels on any pin that is defined as a digital input, may cause the input buffer to consume more current than is specified.

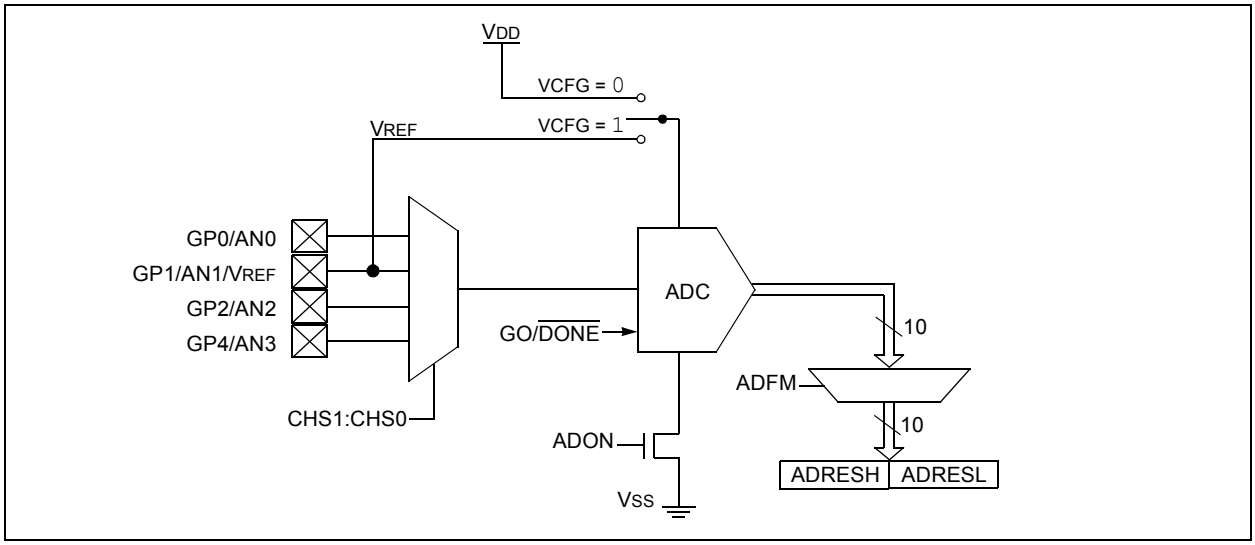
FIGURE 6-4: MODIFIED COMPARATOR OUTPUT BLOCK DIAGRAM



7.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE (PIC12F675 ONLY)

The Analog-to-Digital converter (A/D) allows conversion of an analog input signal to a 10-bit binary representation of that signal. The PIC12F675 has four analog inputs, multiplexed into one sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a binary result via successive approximation and stores the result in a 10-bit register. The voltage reference used in the conversion is software selectable to either VDD or a voltage applied by the VREF pin. Figure 7-1 shows the block diagram of the A/D on the PIC12F675.

FIGURE 7-1: A/D BLOCK DIAGRAM



7.1 A/D Configuration and Operation

There are two registers available to control the functionality of the A/D module:

1. ADCON0 (Register 7-1)
2. ANSEL (Register 7-2)

7.1.1 ANALOG PORT PINS

The ANS3:ANS0 bits (ANSEL<3:0>) and the TRISIO bits control the operation of the A/D port pins. Set the corresponding TRISIO bits to set the pin output driver to its high-impedance state. Likewise, set the corresponding ANS bit to disable the digital input buffer.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

7.1.2 CHANNEL SELECTION

There are four analog channels on the PIC12F675, AN0 through AN3. The CHS1:CHS0 bits (ADCON0<3:2>) control which channel is connected to the sample and hold circuit.

7.1.3 VOLTAGE REFERENCE

There are two options for the voltage reference to the A/D converter: either VDD is used, or an analog voltage applied to VREF is used. The VCFG bit (ADCON0<6>) controls the voltage reference selection. If VCFG is set, then the voltage on the VREF pin is the reference; otherwise, VDD is the reference.

7.1.4 CONVERSION CLOCK

The A/D conversion cycle requires 11 TAD. The source of the conversion clock is software selectable via the ADCS bits (ANSEL<6:4>). There are seven possible clock options:

- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal RC oscillator)

For correct conversion, the A/D conversion clock (1/TAD) must be selected to ensure a minimum TAD of 1.6 μs. Table 7-1 shows a few TAD calculations for selected frequencies.

TABLE 7-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Device Frequency			
Operation	**ADCS2:ADCS0**	**20 MHz**	**5 MHz**	**4 MHz**	**1.25 MHz**
2 TOSC	000	100 ns(2)	400 ns(2)	500 ns(2)	1.6 μs
4 TOSC	100	200 ns(2)	800 ns(2)	1.0 μs(2)	3.2 μs
8 TOSC	001	400 ns(2)	1.6 μs	2.0 μs	6.4 μs
16 TOSC	101	800 ns(2)	3.2 μs	4.0 μs	12.8 μs(3)
32 TOSC	010	1.6 μs	6.4 μs	8.0 μs(3)	25.6 μs(3)
64 TOSC	110	3.2 μs	12.8 μs(3)	16.0 μs(3)	51.2 μs(3)
A/D RC	x11	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The A/D RC source has a typical TAD time of 4 μs for VDD > 3.0V.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the A/D RC clock source is only recommended if the conversion will be performed during Sleep.

7.1.5 STARTING A CONVERSION

The A/D conversion is initiated by setting the GO/$\overline{\text{DONE}}$ bit (ADCON0<1>). When the conversion is complete, the A/D module:

- Clears the GO/$\overline{\text{DONE}}$ bit
- Sets the ADIF flag (PIR1<6>)
- Generates an interrupt (if enabled)

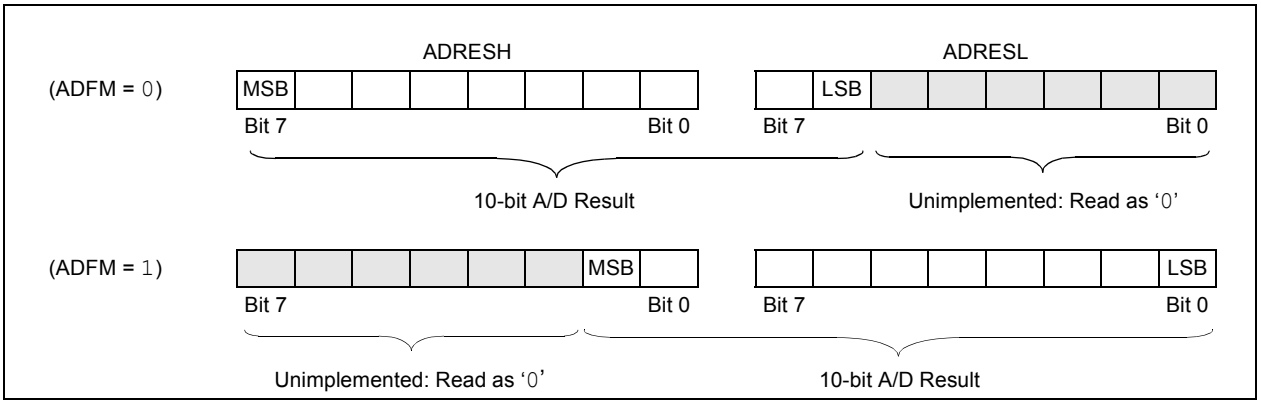
If the conversion must be aborted, the GO/$\overline{\text{DONE}}$ bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete A/D conversion sample. Instead, the ADRESH:ADRESL registers will retain the value of the previous conversion. After an aborted conversion, a 2 TAD delay is required before another acquisition can be initiated. Following the delay, an input acquisition is automatically started on the selected channel.

Note:	The GO/$\overline{\text{DONE}}$ bit should not be set in the same instruction that turns on the A/D.

7.1.6 CONVERSION OUTPUT

The A/D conversion can be supplied in two formats: left or right shifted. The ADFM bit (ADCON0<7>) controls the output format. Figure 7-2 shows the output formats.

FIGURE 7-2: 10-BIT A/D RESULT FORMAT



9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC12F629/675 can be operated in eight different oscillator option modes. The user can program three Configuration bits (FOSC2 through FOSC0) to select one of these eight modes:

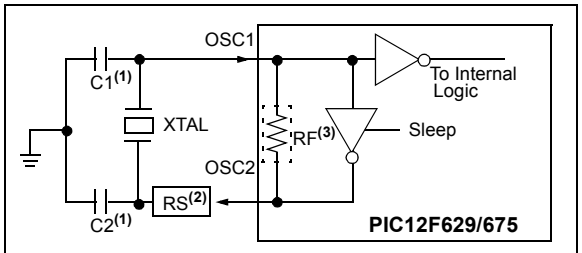
- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High-Speed Crystal/Resonator
- RC External Resistor/Capacitor (2 modes)
- INTOSC Internal Oscillator (2 modes)
- EC External Clock In

Note: Additional information on oscillator configurations is available in the PIC® Mid-Range Reference Manual, (DS33023).

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

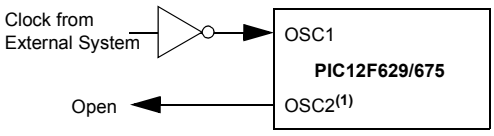
In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (see Figure 9-1). The PIC12F629/675 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may yield a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (see Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) HS, XT OR LP OSC CONFIGURATION



Note 1: See Table 9-1 and Table 9-2 for recommended values of C1 and C2.
2: A series resistor may be required for AT strip cut crystals.
3: RF varies with the Oscillator mode selected (Approx. value = 10 MΩ).

FIGURE 9-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT, EC, OR LP OSC CONFIGURATION)



Note 1: Functions as GP4 in EC Osc mode.

TABLE 9-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Ranges Characterized:			
Mode	**Freq.**	**OSC1(C1)**	**OSC2(C2)**
XT	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-68 pF 15-68 pF	68-100 pF 15-68 pF 15-68 pF
HS	8.0 MHz 16.0 MHz	10-68 pF 10-22 pF	10-68 pF 10-22 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Mode	Freq.	OSC1(C1)	OSC2(C2)
LP	32 kHz	68-100 pF	68-100 pF
XT	100 kHz 2 MHz 4 MHz	68-150 pF 15-30 pF 15-30 pF	150-200 pF 15-30 pF 15-30 pF
HS	8 MHz 10 MHz 20 MHz	15-30 pF 15-30 pF 15-30 pF	15-30 pF 15-30 pF 15-30 pF

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

9.2.3 EXTERNAL CLOCK IN

For applications where a clock is already available elsewhere, users may directly drive the PIC12F629/675 provided that this external clock source meets the AC/DC timing requirements listed in **Section 12.0 "Electrical Specifications"**. Figure 9-2 shows how an external clock circuit should be configured.

9.2.4 RC OSCILLATOR

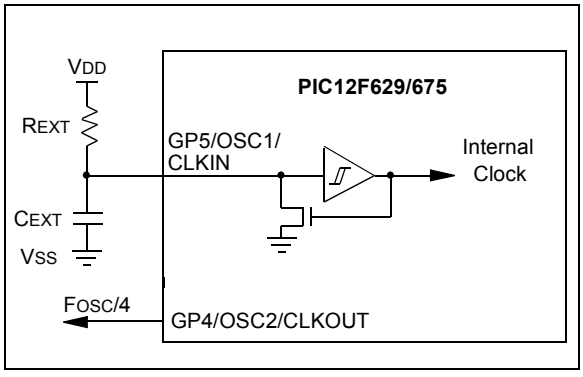
For applications where precise timing is not a requirement, the RC oscillator option is available. The operation and functionality of the RC oscillator is dependent upon a number of variables. The RC oscillator frequency is a function of:

- Supply voltage
- Resistor (REXT) and capacitor (CEXT) values
- Operating temperature.

The oscillator frequency will vary from unit to unit due to normal process parameter variation. The difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to account for the tolerance of the external R and C components. Figure 9-3 shows how the R/C combination is connected.

Two options are available for this Oscillator mode which allow GP4 to be used as a general purpose I/O or to output FOSC/4.

FIGURE 9-3: RC OSCILLATOR MODE



9.2.5 INTERNAL 4 MHz OSCILLATOR

When calibrated, the internal oscillator provides a fixed 4 MHz (nominal) system clock. See Electrical Specifications, **Section 12.0 "Electrical Specifications"**, for information on variation over voltage and temperature.

Two options are available for this Oscillator mode which allow GP4 to be used as a general purpose I/O or to output FOSC/4.

9.2.5.1 Calibrating the Internal Oscillator

A calibration instruction is programmed into the last location of program memory. This instruction is a `RETLW XX`, where the literal is the calibration value. The literal is placed in the OSCCAL register to set the calibration of the internal oscillator. Example 9-1 demonstrates how to calibrate the internal oscillator. For best operation, decouple (with capacitance) VDD and VSS as close to the device as possible.

Note:	Erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be saved prior to erasing part as specified in the PIC12F629/675 Programming specification. Microchip Development Tools maintain all Calibration bits to factory settings.

EXAMPLE 9-1: CALIBRATING THE INTERNAL OSCILLATOR

```
BSF     STATUS, RP0     ;Bank 1
CALL    3FFh            ;Get the cal value
MOVWF   OSCCAL          ;Calibrate
BCF     STATUS, RP0     ;Bank 0
```

9.2.6 CLKOUT

The PIC12F629/675 devices can be configured to provide a clock out signal in the INTOSC and RC oscillator modes. When configured, the oscillator frequency divided by four (FOSC/4) is output on the GP4/OSC2/CLKOUT pin. FOSC/4 can be used for test purposes or to synchronize other logic.

9.3 Reset

The PIC12F629/675 differentiates between various kinds of Reset:

a) Power-on Reset (POR)
b) WDT Reset during normal operation
c) WDT Reset during Sleep
d) $\overline{\text{MCLR}}$ Reset during normal operation
e) $\overline{\text{MCLR}}$ Reset during Sleep
f) Brown-out Detect (BOD)

Some registers are not affected in any Reset condition; their status is unknown on POR and unchanged in any other Reset. Most other registers are reset to a "Reset state" on:

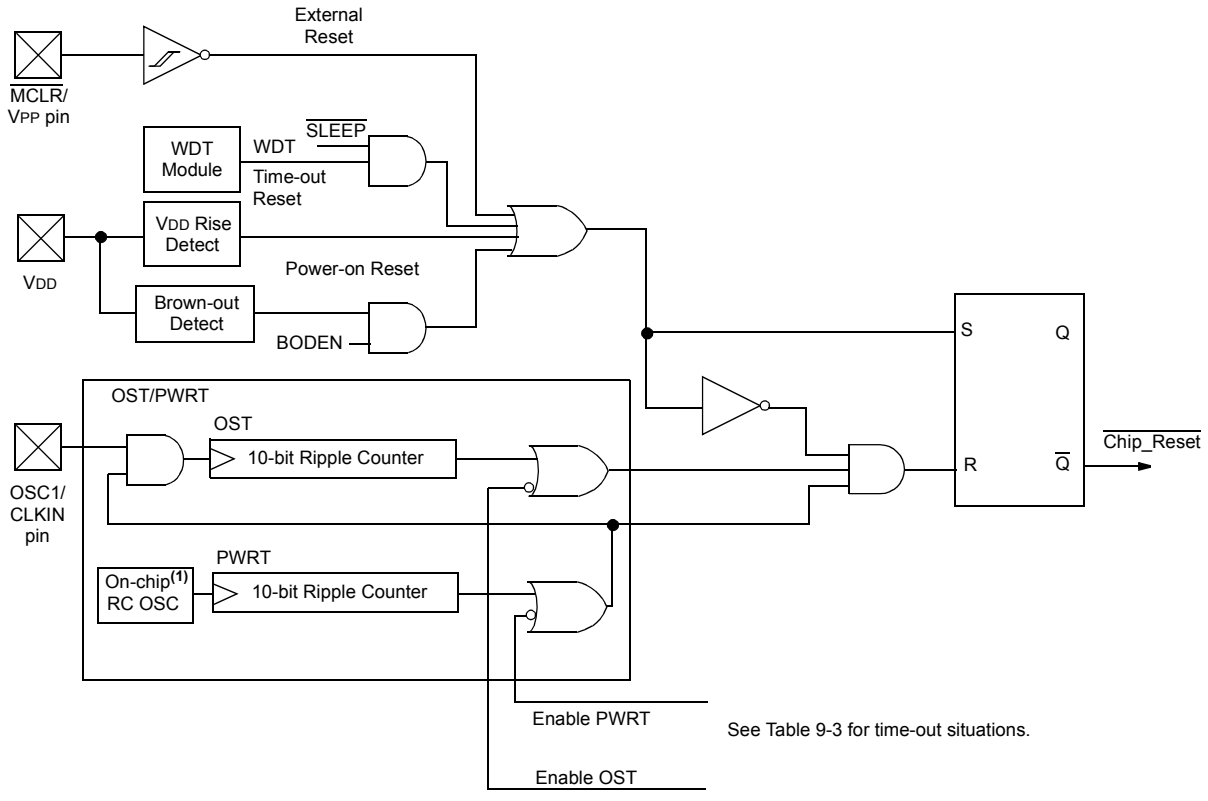
- Power-on Reset
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- WDT Reset during Sleep
- Brown-out Detect (BOD) Reset

They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different Reset situations as indicated in Table 9-4. These bits are used in software to determine the nature of the Reset. See Table 9-7 for a full description of Reset states of all registers.

A simplified block diagram of the on-chip Reset Circuit is shown in Figure 9-4.

The $\overline{\text{MCLR}}$ Reset path has a noise filter to detect and ignore small pulses. See Table 12-4 in Electrical Specifications Section for pulse-width specification.

FIGURE 9-4: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the INTOSC/EC oscillator.

9.3.5 BROWN-OUT DETECT (BOD)

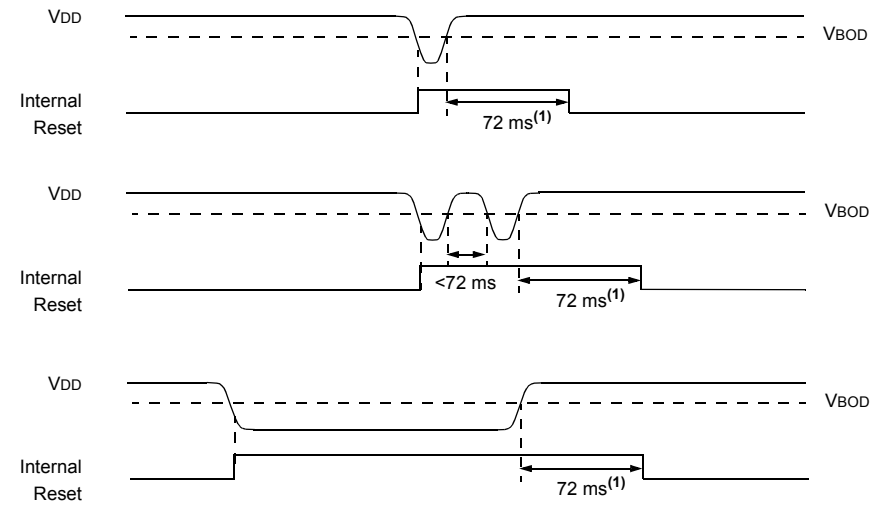
The PIC12F629/675 members have on-chip Brown-out Detect circuitry. A Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Detect circuitry. If VDD falls below VBOD for greater than parameter (TBOD) in Table 12-4 (see **Section 12.0 "Electrical Specifications"**), the Brown-out situation will reset the device. This will occur regardless of VDD slew-rate. A Reset is not guaranteed to occur if VDD falls below VBOD for less than parameter (TBOD).

On any Reset (Power-on, Brown-out, Watchdog, etc.), the chip will remain in Reset until VDD rises above BVDD (see Figure 9-6). The Power-up Timer will now be invoked, if enabled, and will keep the chip in Reset an additional 72 ms.

Note:	A Brown-out Detect does not enable the Power-up Timer if the $\overline{\text{PWRTE}}$ bit in the Configuration Word is set.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Detect and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms Reset.

FIGURE 9-6: BROWN-OUT SITUATIONS



Note 1: 72 ms delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

9.3.6 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: first, PWRT time-out is invoked after POR has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in EC mode with $\overline{\text{PWRTE}}$ bit erased (PWRT disabled), there will be no time-out at all. Figure 9-7, Figure 9-8 and Figure 9-9 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 9-8). This is useful for testing purposes or to synchronize more than one PIC12F629/675 device operating in parallel.

Table 9-6 shows the Reset conditions for some special registers, while Table 9-7 shows the Reset conditions for all the registers.

9.3.7 POWER CONTROL (PCON) STATUS REGISTER

The power CONTROL/STATUS register, PCON (address 8Eh) has two bits.

Bit 0 is $\overline{\text{BOD}}$ (Brown-out). $\overline{\text{BOD}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOD}}$ = 0, indicating that a brown-out has occurred. The $\overline{\text{BOD}}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by setting $\overline{\text{BODEN}}$ bit = 0 in the Configuration Word).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a '0' on Power-on Reset and unaffected otherwise. The user must write a '1' to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is '0', it will indicate that a Power-on Reset must have occurred (i.e., VDD may have gone too low).

TABLE 9-7: INITIALIZATION CONDITION FOR REGISTERS

Register	Address	Power-on Reset	• MCLR Reset during normal operation • MCLR Reset during Sleep • WDT Reset • Brown-out Detect(1)	• Wake-up from Sleep through interrupt • Wake-up from Sleep through WDT Time-out
W	—	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h/80h	—	—	—
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h/82h	0000 0000	0000 0000	PC + 1(3)
STATUS	03h/83h	0001 1xxx	000q quuu(4)	uuuq quuu(4)
FSR	04h/84h	xxxx xxxx	uuuu uuuu	uuuu uuuu
GPIO	05h	--xx xxxx	--uu uuuu	--uu uuuu
PCLATH	0Ah/8Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh/8Bh	0000 0000	0000 000u	uuuu uuqq(2)
PIR1	0Ch	00-- 0--0	00-- 0--0	qq-- q--q(2,5)
T1CON	10h	-000 0000	-uuu uuuu	-uuu uuuu
CMCON	19h	-0-0 0000	-0-0 0000	-u-u uuuu
ADRESH	1Eh	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	1Fh	00-- 0000	00-- 0000	uu-- uuuu
OPTION_REG	81h	1111 1111	1111 1111	uuuu uuuu
TRISIO	85h	--11 1111	--11 1111	--uu uuuu
PIE1	8Ch	00-- 0--0	00-- 0--0	uu-- u--u
PCON	8Eh	---- --0x	---- --uu(1,6)	---- --uu
OSCCAL	90h	1000 00--	1000 00--	uuuu uu--
WPU	95h	--11 -111	--11 -111	uuuu uuuu
IOC	96h	--00 0000	--00 0000	--uu uuuu
VRCON	99h	0-0- 0000	0-0- 0000	u-u- uuuu
EEDATA	9Ah	0000 0000	0000 0000	uuuu uuuu
EEADR	9Bh	-000 0000	-000 0000	-uuu uuuu
EECON1	9Ch	---- x000	---- q000	---- uuuu
EECON2	9Dh	---- ----	---- ----	---- ----
ADRESL	9Eh	xxxx xxxx	uuuu uuuu	uuuu uuuu
ANSEL	9Fh	-000 1111	-000 1111	-uuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.

Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON and/or PIR1 will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 9-6 for Reset value for specific condition.

5: If wake-up was due to data EEPROM write completing, Bit 7 = 1; A/D conversion completing, Bit 6 = 1; Comparator input changing, bit 3 = 1; or Timer1 rolling over, bit 0 = 1. All other interrupts generating a wake-up will cause these bits to = u.

6: If Reset was due to brown-out, then bit 0 = 0. All other Resets will cause bit 0 = u.

9.4.1 GP2/INT INTERRUPT

External interrupt on GP2/INT pin is edge-triggered; either rising if INTEDG bit (OPTION<6>) is set, of falling, if INTEDG bit is clear. When a valid edge appears on the GP2/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the Interrupt Service Routine before re-enabling this interrupt. The GP2/INT interrupt can wake-up the processor from Sleep if the INTE bit was set prior to going into Sleep. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See **Section 9.7 "Power-Down Mode (Sleep)"** for details on Sleep and Figure 9-13 for timing of wake-up from Sleep through GP2/INT interrupt.

Note:	The ANSEL (9Fh) and CMCON (19h) registers must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'. The ANSEL register is defined for the PIC12F675.

9.4.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see **Section 4.0 "Timer0 Module"**.

9.4.3 GPIO INTERRUPT

An input change on GPIO change sets the GPIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the GPIE (INTCON<3>) bit. Plus individual pins can be configured through the IOC register.

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the GPIF interrupt flag may not get set.

9.4.4 COMPARATOR INTERRUPT

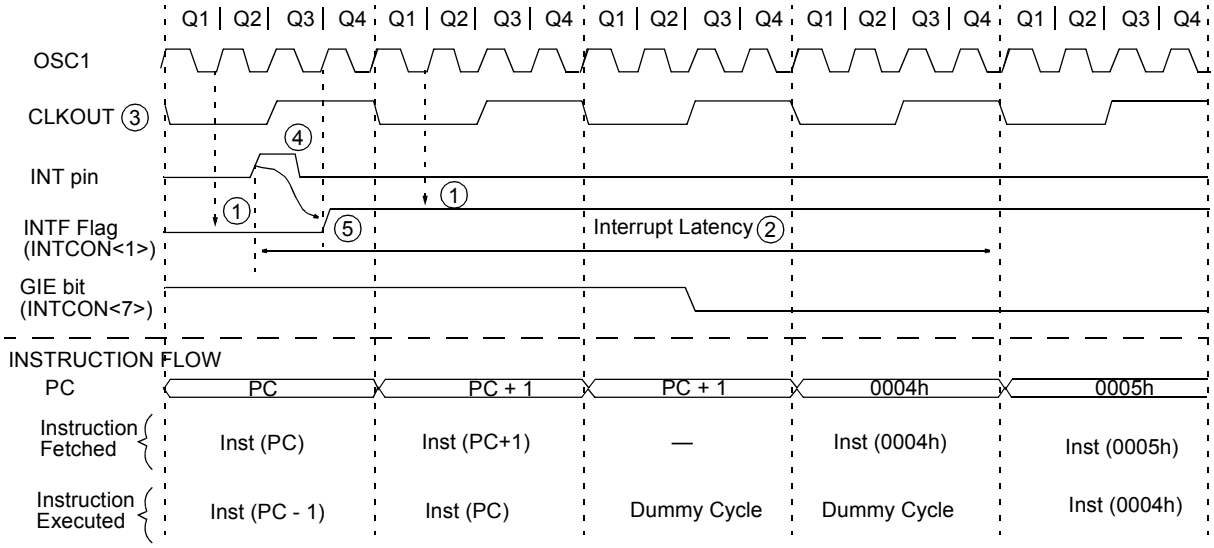
See **Section 6.9 "Comparator Interrupts"** for description of comparator interrupt.

9.4.5 A/D CONVERTER INTERRUPT

After a conversion is complete, the ADIF flag (PIR<6>) is set. The interrupt can be enabled/disabled by setting or clearing ADIE (PIE<6>).

See **Section 7.0 "Analog-to-Digital Converter (A/D) Module (PIC12F675 only)"** for operation of the A/D converter interrupt.

FIGURE 9-11: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-4 TCY. Synchronous latency = 3 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in RC Oscillator mode.

4: For minimum width of INT pulse, refer to AC specs.

5: INTF is enabled to be set any time during the Q4-Q1 cycles.

MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Description: The contents of register f is moved to a destination dependent upon the status of d. If d = 0, the destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example:
```
MOVF    FSR, 0
```
After Instruction
W = value in FSR register
Z = 1

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: $0 \le k \le 255$

Operation: k → (W)

Status Affected: None

Description: The eight-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 127$

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   OPTION
```
Before Instruction
OPTION = 0xFF
W = 0x4F
After Instruction
OPTION = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Description: No operation.

Words: 1

Cycles: 1

Example:
```
NOP
```

NOTES:

FIGURE 13-3: TYPICAL IPD vs. VDD OVER TEMP (+125°C)

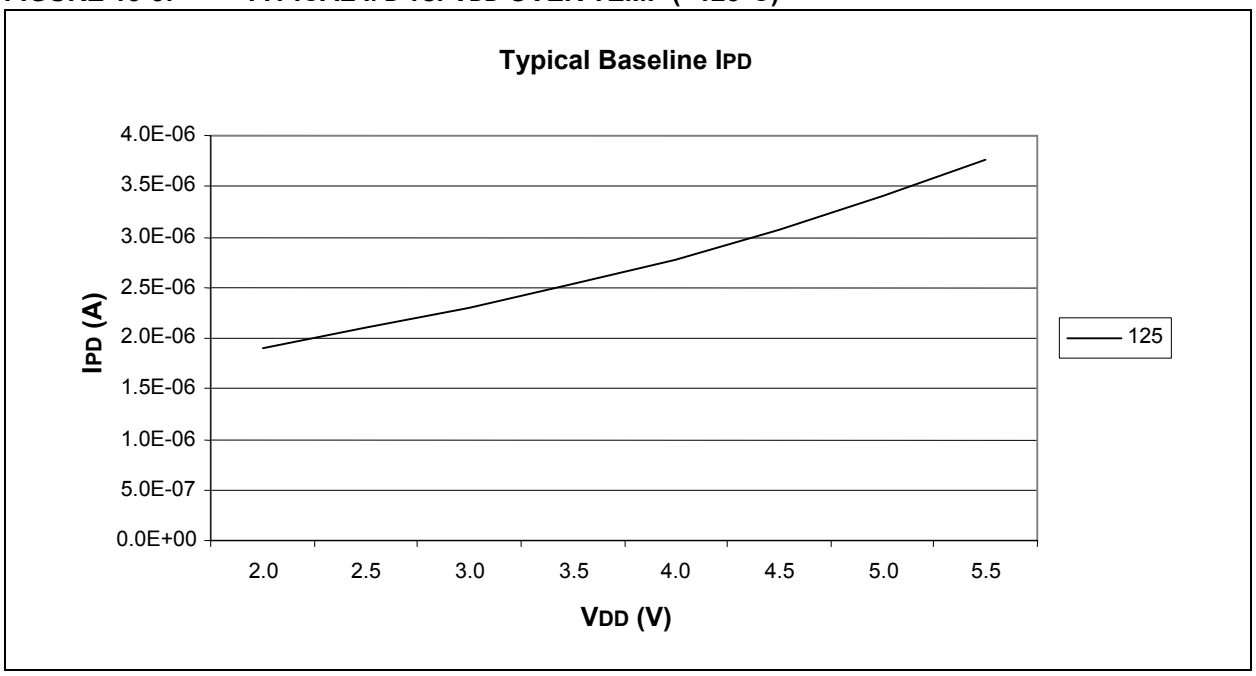


FIGURE 13-4: MAXIMUM IPD vs. VDD OVER TEMP (-40°C TO +25°C)

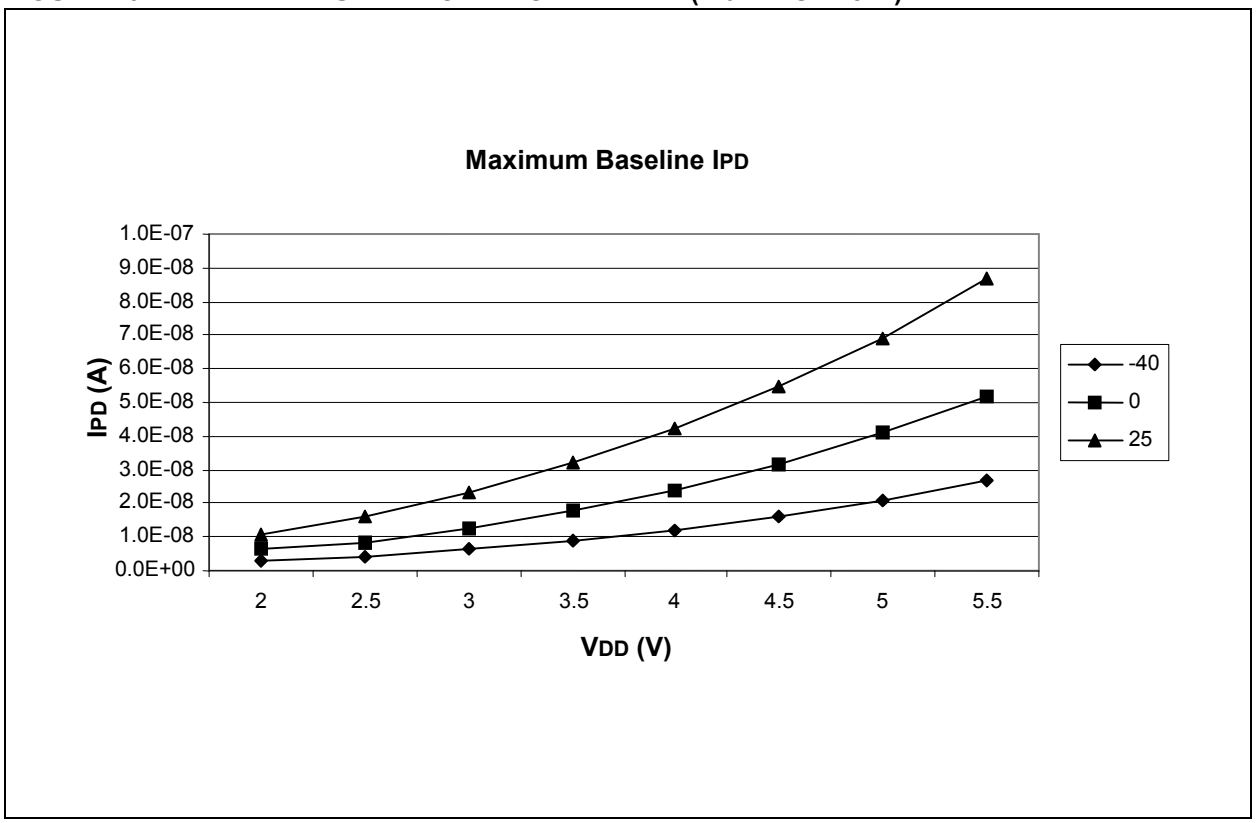


FIGURE 13-15: MAXIMUM AND MINIMUM INTOSC FREQ vs. TEMPERATURE WITH 0.1μF AND 0.01μF DECOUPLING (V_{DD} = 3.5V)

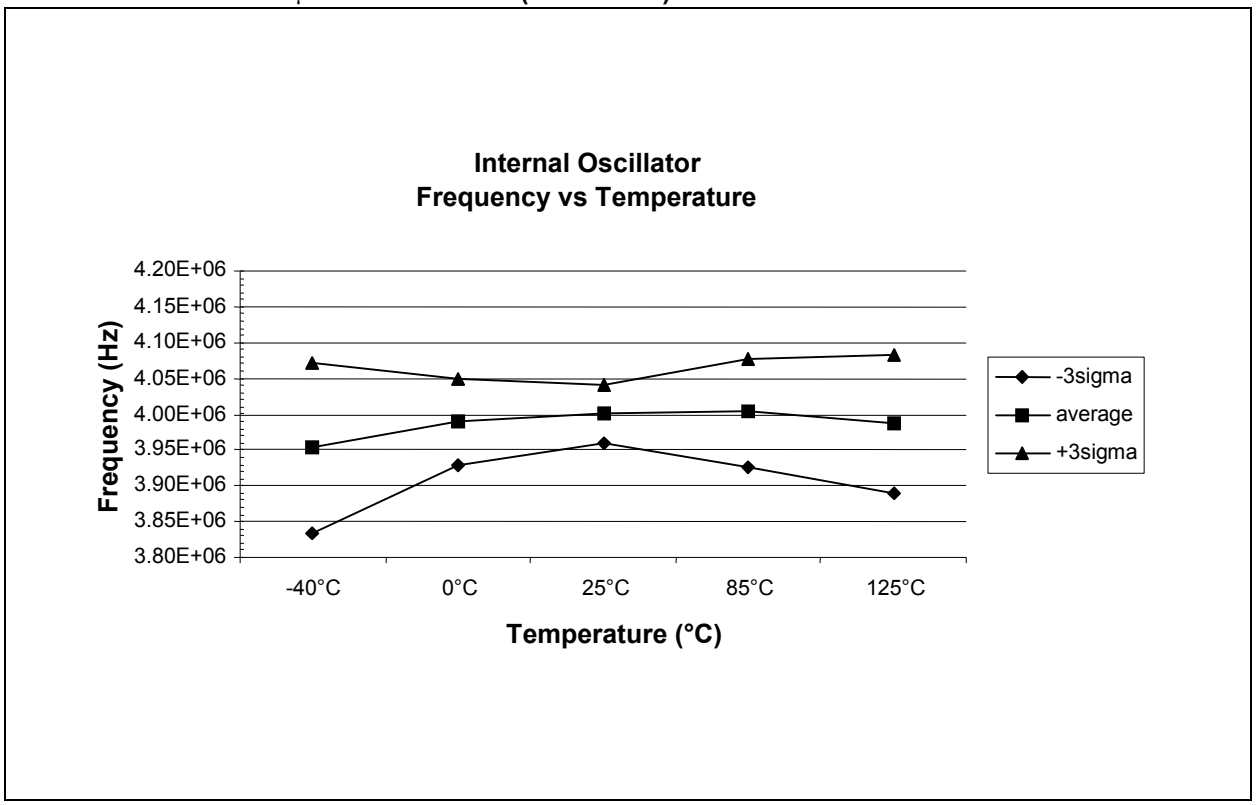
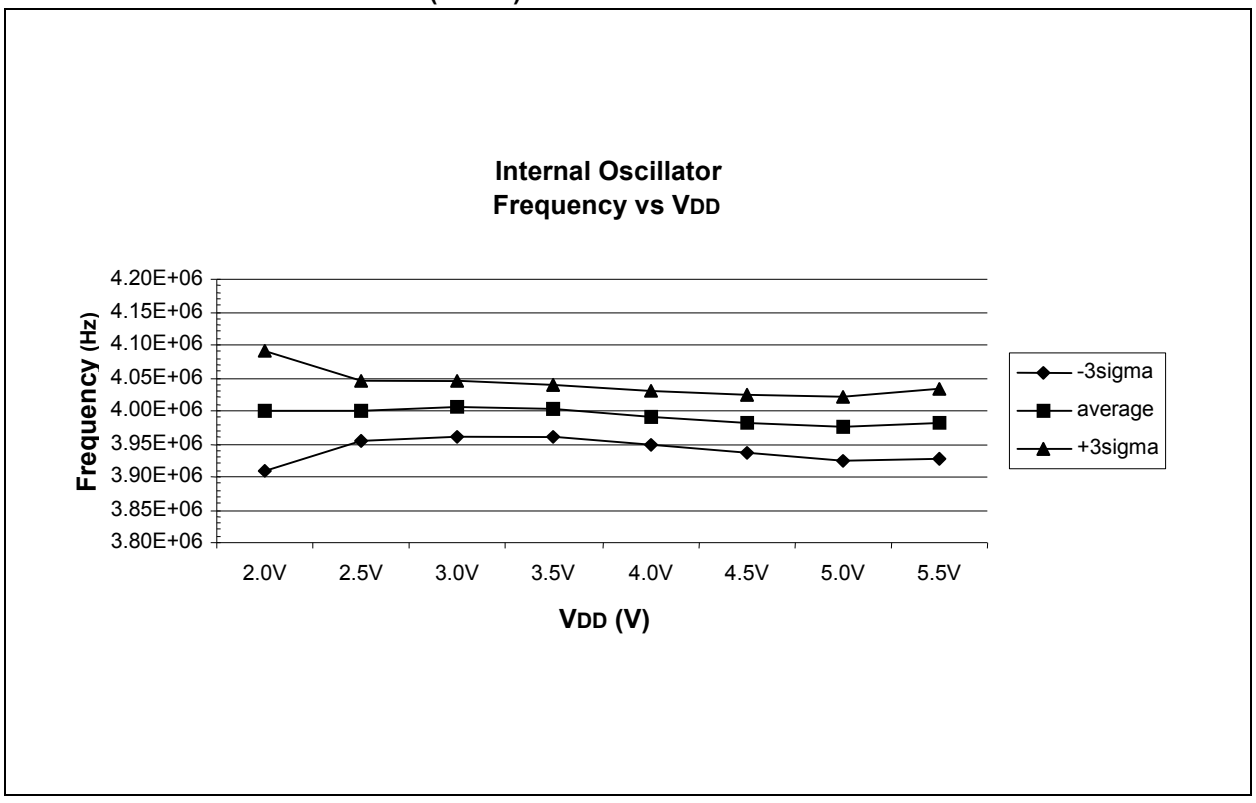
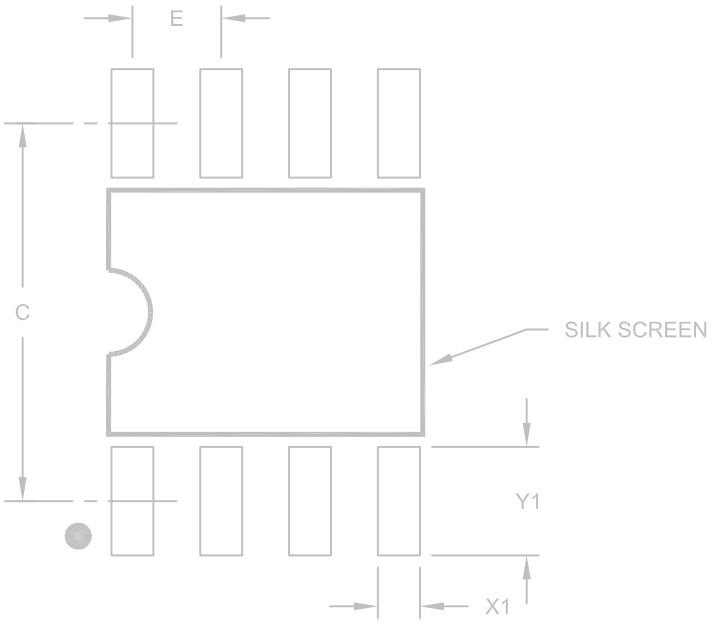


FIGURE 13-16: MAXIMUM AND MINIMUM INTOSC FREQ vs. V_{DD} WITH 0.1μF AND 0.01μF DECOUPLING (+25°C)



8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

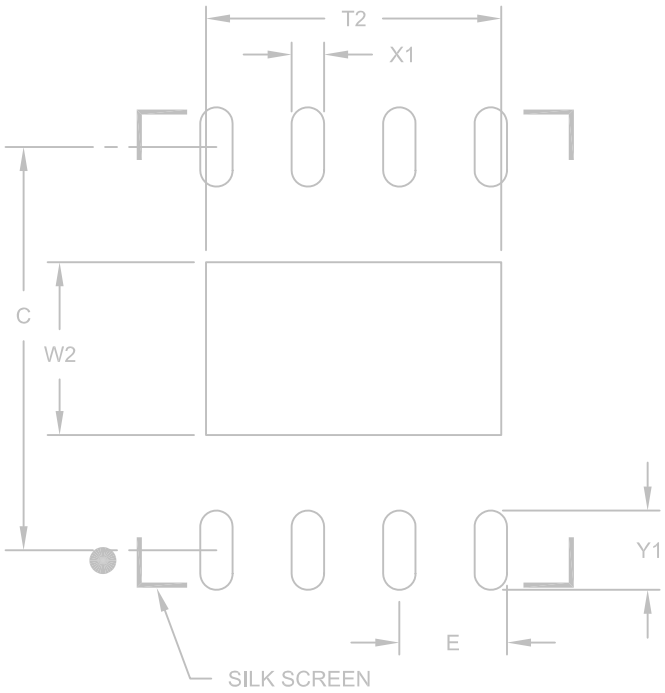
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

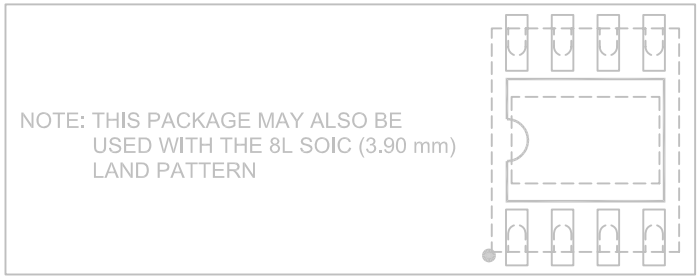
Microchip Technology Drawing No. C04-2057A

8-Lead Plastic Dual Flat, No Lead Package (MF) - 6x5 mm Body [DFN-S]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Optional Center Pad Width	W2			2.40
Optional Center Pad Length	T2			4.10
Contact Pad Spacing	C		5.60	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.10

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2122A